International Interconnect Technology Conference Call for Papers

BURLINGAME, CA -- The 13th annual IEEE International Interconnect Technology Conference (IITC) and exhibition has announced a Call for Papers for work describing innovative developments in the critically important field of interconnections for electronic systems. The conference seeks papers on all aspects of interconnects for device, circuit board and system-level applications. The deadline for submission of paper abstracts is Feb. 1, 2010.

IITC 2010 will be held June 7-9 at the Hyatt Regency San Francisco Airport Hotel in Burlingame. It will be preceded by a day-long Short Course on leading-edge interconnect technologies on Sunday, June 6. The conference attracts professionals in semiconductor processing, interconnect design, academia and equipment development. The traditional U.S. venue is now one of three international locations for this important technology conference, which rotates among them annually. In 2009, IITC was held in Sapporo, Japan, while the 2011 edition will take place in Europe.

"Interconnections have become tremendously important in recent years because of their potential to become bottlenecks to higher performance, and because they are key to achieving some of the most exciting ideas in electronics, such as 3D systems. This year new, relevant focus areas have been added, including the relationship of device interconnects with system-level interconnections and interfaces," said Michael Armacost, IITC 2010 Publicity Chair and Managing Director at Applied Materials, Inc. "The IITC conference is a premier global forum for specialists and suppliers to come together to discuss, demonstrate and exhibit advanced interconnect techniques, materials, architectures and processes that shed light on the best ways forward."

IITC 2010 is seeking papers in the areas of process integration (for logic and/or memory); reliability; advanced interconnects and systems interconnections; through-silicon vias and 3D integration; packaging; novel materials and concepts; process modeling, and all back-end materials and unit processes associated with interconnect technology, including in-depth explorations of related manufacturing issues.

Papers from universities, national laboratories, semiconductor manufacturers, foundries, and equipment/materials suppliers are encouraged. Following a rigorous review, papers will be selected for either oral presentations or poster presentations during the exhibition hours. In addition, papers will be selected for a special poster session for new engineers and students.

The IITC 2010 Call for Papers and paper-submission requirements can be found on

the conference website, http://www.ieee.org/conference/iitc [1]. A limited number of papers reporting the latest breakthroughs may be accepted as late-news papers. The late-news deadline is March 26, 2010.

Additional information about IEEE can be found at http://www.ieee.org [2].

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